

Final Product Change Notification

202306051F01: NX5P3001UK New BOM Qualification at ASEK

Note: This notice is NXP Company Proprietary.

Issue Date: Jul 12, 2023 Effective date:Oct 10, 2023

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Management summary

Changing of repassivation from PI to PBO on NX5P3001UK at ASEK due to supplier discontinuation.

Change Category

[]Wafer Fab Process	[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[X]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Wafer Fab Location	[]Assembly Location	[]Packing/Shipping/Labeling	[]Test Location	[]Electrica spec./Test coverage
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[]Firmware []Other

Description

PCN Overview

Changing of repassivation from PI to PBO due to supplier discontinuation.

Repassivation: change before is I-8124ER1 and change after is HD8820

UBM: change before is Ti/NiV/Cu and change after is Ti/Cu/Cu

It should be noted that the above configuration is a current standard and is in high volume manufacturing.

Note: There was previously a update (20230517) as listed in the currently available datasheet where the

package outline (max/nom/min dimensions for "b") was corrected. The original data was incorrect.

is/was not change to the product from the dimensional aspect.

Reason

There

Changing of repassivation from PI to PBO due to supplier discontinuation.

Identification of Affected Products

Top Side Marking

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipmentOct 16, 2023

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification:view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Aug 11, 2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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